

— **Call for Papers** —
A Symposium on
Monitoring, Sensing, and Control for Intelligent Machining and Inspection

Sponsored by the ASME Manufacturing Engineering Division's
Manufacturing Processes Technical Committee
2017 ASME International Manufacturing Science and Engineering Conference (MSEC)*
June 4-8, 2017
University of Southern California

Technical Focus

Today's increasingly complex industrial processes require advanced automated systems to achieve dramatic gains in productivity and product quality. With better utilization of sensors, system models, algorithms and computational methods, substantial improvements to the production cost and operational quality can be achieved. This symposium will focus on monitoring, sensing, and control that aid in the automation of manufacturing processes, elimination and control of quality variation in production, and optimization of the manufacturing processes. Papers should include novel theoretical contributions or applications. It is preferable to have theoretical results complemented with experimental evaluations. Papers from the industrial sector and papers related to the conference highlight topics are strongly encouraged. Specific topics of interest include, but are not limited to:

- Monitoring and control of manufacturing equipment and processes
- Sensor design, integration and fusion
- Supervisory systems and factory automation
- Adaptive machining and control
- Tool condition monitoring
- Machine tool performance characterization
- Product quality inspection using machine vision and laser technologies
- Big data and advanced analytics for smart manufacturing
- MTConnect-based applications for manufacturing

Paper Submission

Authors are encouraged to submit an abstract and full manuscript for review by **November 03, 2016** via the conference website. Final revised manuscripts must be submitted by **March 08, 2017**. The copyright transfer form must be filled out and the presenting author must pre-register by April 06, 2017 or the paper will be withdrawn from the conference. Authors may also consult www.asme.org/divisions/med/call/ for updates. **No papers are to be submitted to the organizers; submissions will only be accepted via the conference website at www.asmeconferences.org/msec2017/.**

Additional Symposium Activities

To highlight advancements in this technical area, symposium organizers will work to attract a high profile international keynote speaker including honorarium

Organizers

Dr. Radu Pavel, TechSolve, Inc., Cincinnati, OH, USA, Ph: 513-948-2062, pavel@techsolve.org
Prof. Samuel H. Huang, University of Cincinnati, Cincinnati, OH, USA, Ph: 513-556-1154, sam.huang@uc.edu

* The conference is collocated with NAMRI/SME's 45th North American Manufacturing Research Conference (NAMRC45) and JSME's International Conference on Materials and Processing (ICMP 2017), both of which have a separate call-for-papers. Please note that submissions of the same paper to more than one conference are not permitted.